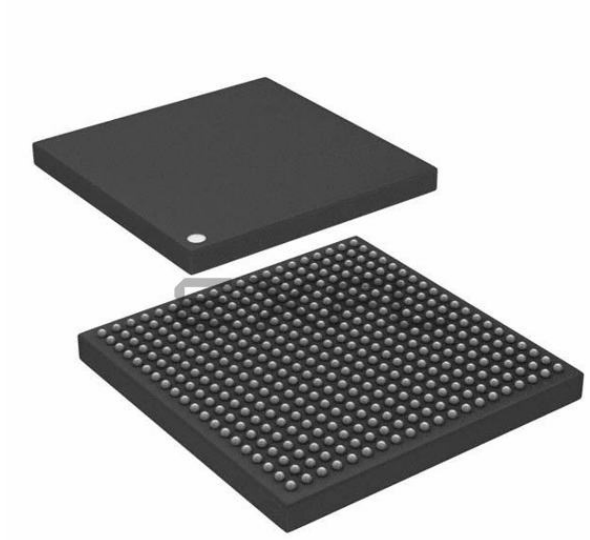

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Understanding Embedded - DSP (Digital Signal Processors)

Embedded - DSP (Digital Signal Processors) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of Embedded - DSP (Digital Signal Processors)

Details	
Product Status	Obsolete
Type	SC1400 Core
Interface	Host Interface, I²C, UART
Clock Rate	266MHz
Non-Volatile Memory	External
On-Chip RAM	208kB
Voltage - I/O	3.30V
Voltage - Core	1.20V
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	400-LFBGA
Supplier Device Package	400-LFBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/msc7113vf1000

Bottom View

	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1
A	NC	NC	NC	NC	NC	GND	HD0	HD1	HD4	HD6	HD7	HD10	HD12	HD15	$\overline{CK}$	CK	DQS2	DQM1	GND	GND
B	NC	NC	NC	NC	NC	NC	NC	HD2	HD5	HD8	HD11	HD14	$\overline{WE}$	CKE	DQS0	DQS3	DQM2	$\overline{CS0}$	NC	V_{DDM}
C	NC	NC	NC	NC	NC	NC	NC	NC	HD3	HD9	HD13	$\overline{CAS}$	$\overline{RAS}$	DQS1	DQM0	DQM3	$\overline{CS1}$	D25	D30	D24
D	NC	NC	NC	V_{DD}	V_{DDIO}	V_{DDIO}	V_{DDIO}	V_{DDIO}	V_{DDIO}	V_{DDIO}	V_{DDM}	V_{DDM}	V_{DDM}	V_{DDM}	V_{DDM}	V_{DDM}	GND	D27	D28	V_{DDM}
E	NC	NC	NC	V_{DD}	V_{DD}	V_{DDIO}	V_{DDIO}	V_{DDIO}	V_{DDIO}	V_{DDIO}	V_{DDM}	V_{DD}	V_{DD}	V_{DD}	V_{DD}	V_{DDM}	V_{DDM}	D31	D26	GND
F	NC	NC	NC	V_{DD}	V_{DD}	V_{DDIO}	GND	GND	GND	V_{DDM}	V_{DDM}	GND	GND	GND	V_{DD}	V_{DD}	V_{DD}	D29	D15	V_{DDM}
G	NC	NC	NC	V_{DD}	V_{DDIO}	V_{DDIO}	GND	GND	GND	GND	GND	GND	GND	GND	GND	V_{DDM}	V_{DDM}	GND	D13	GND
H	HA1	HA2	NC	V_{DD}	V_{DDIO}	V_{DDIO}	GND	GND	GND	GND	GND	GND	GND	GND	GND	V_{DDM}	V_{DDM}	D11	D12	D14
J	$\overline{HREQ}$	$\overline{HACK}$	HA3	V_{DD}	V_{DDIO}	GND	GND	GND	GND	GND	GND	GND	GND	GND	V_{DDM}	V_{DDM}	V_{DDM}	D9	V_{DDM}	D10
K	$\overline{HDS}$	HDDS	HA0	V_{DD}	V_{DDIO}	V_{DDIO}	GND	GND	GND	GND	GND	GND	GND	GND	GND	V_{DDM}	V_{DD}	D8	GND	D0
L	HRW	$\overline{HCS1}$	$\overline{HCS2}$	V_{DD}	V_{DDIO}	V_{DDIO}	V_{DDIO}	GND	GND	GND	GND	GND	GND	GND	GND	V_{DDM}	V_{DD}	D3	GND	D1
M	URXD	UTXD	SDA	V_{DD}	V_{DD}	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	V_{DDM}	V_{DDM}	D5	V_{DDM}	D2
N	V_{SSPLL}	SCL	CLKIN	V_{DD}	V_{DD}	V_{DDIO}	GND	GND	GND	GND	GND	GND	GND	GND	V_{DDM}	V_{DDM}	V_{DDM}	V_{REF}	D6	D4
P	V_{DDPLL}	TPSEL	$\overline{PORESET}$	V_{DD}	V_{DDIO}	V_{DDIO}	GND	GND	GND	GND	GND	GND	GND	GND	V_{DDM}	V_{DDM}	V_{DDM}	D16	D17	D7
R	TEST0	EE0	TDO	V_{DD}	V_{DDIO}	V_{DDIO}	GND	V_{DDIO}	GND	GND	V_{DDM}	GND	V_{DDM}	GND	V_{DDM}	V_{DDM}	V_{DDM}	D18	D19	GND
T	$\overline{HRESET}$	TMS	MDIO	V_{DD}	V_{DD}	V_{DDIO}	V_{DDIO}	V_{DDIO}	V_{DDIO}	V_{DDM}	V_{DDM}	V_{DD}	V_{DDM}	V_{DDM}	V_{DD}	V_{DDM}	V_{DDM}	D22	D20	V_{DDM}
U	$\overline{TRST}$	TCK	COL	V_{DD}	V_{DD}	V_{DD}	V_{DD}	V_{DD}	V_{DD}	V_{DD}	V_{DD}	V_{DD}	V_{DD}	V_{DD}	V_{DD}	V_{DD}	V_{DDM}	D23	D21	GND
V	TDI	CRS	TX_EN	RXD0	RXD2	TX_ER	T1TD	T1RFS	T0TCK	EVNT4	EVNT0	NC	BA0	A2	A5	A10	A11	A13	NC	V_{DDM}
W	MDC	RX_ER	TXCLK	TXD1	RXD3	TXD2	T1TFS	T1RD	T0TFS	T0RFS	EVNT2	EVNT1	NC	A3	A6	A7	A8	A12	V_{DDM}	GND
Y	RX_DV	GND	RXD1	TXD0	RXCLK	TXD3	T1TCK	T1RCK	TOTD	T0RD	T0RCK	EVNT3	$\overline{NMI}$	BA1	A4	A0	A1	A9	GND	V_{DDM}

Figure 3. MSC7113 Molded Array Process-Ball Grid Array (MAP-BGA), Bottom View

1.2 Signal List By Ball Location

Table 1 lists the signals sorted by ball number and configuration.

Table 1. MSC7113 Signals by Ball Designator

Number	Signal Names					
	End of Reset	Software Controlled			Hardware Controlled	
		GPI Enabled (Default)	Interrupt Enabled	GPO Enabled	Primary	Alternate
A1	GND					
A2	GND					
A3	DQM1					
A4	DQS2					
A5	CK					
A6	$\overline{CK}$					
A7	GPIC7			GPOC7	HD15	
A8	GPIC4			GPOC4	HD12	
A9	GPIC2			GPOC2	HD10	
A10	reserved				HD7	
A11	reserved				HD6	
A12	reserved				HD4	
A13	reserved				HD1	
A14	reserved				HD0	
A15	GND					
A16 (1L44X)	NC					
A16 (1M88B)	BM3	GPID8		GPOD7	reserved	
A17	NC					
A18	NC					
A19	NC					
A20	NC					
B1	V_{DDM}					
B2	NC					
B3	$\overline{CS0}$					
B4	DQM2					
B5	DQS3					
B6	DQS0					
B7	CKE					
B8	$\overline{WE}$					
B9	GPIC6			GPOC6	HD14	
B10	GPIC3			GPOC3	HD11	
B11	GPIC0			GPOC0	HD8	
B12	reserved				HD5	
B13	reserved				HD2	
B14	NC					

Table 1. MSC7113 Signals by Ball Designator (continued)

Number	Signal Names					
	End of Reset	Software Controlled			Hardware Controlled	
		GPI Enabled (Default)	Interrupt Enabled	GPO Enabled	Primary	Alternate
D12	V_{DDIO}					
D13	V_{DDIO}					
D14	V_{DDIO}					
D15	V_{DDIO}					
D16	V_{DDIO}					
D17	V_{DDC}					
D18	NC					
D19	NC					
D20	NC					
E1	GND					
E2	D26					
E3	D31					
E4	V_{DDM}					
E5	V_{DDM}					
E6	V_{DDC}					
E7	V_{DDC}					
E8	V_{DDC}					
E9	V_{DDC}					
E10	V_{DDM}					
E11	V_{DDIO}					
E12	V_{DDIO}					
E13	V_{DDIO}					
E14	V_{DDIO}					
E15	V_{DDIO}					
E16	V_{DDC}					
E17	V_{DDC}					
E18	NC					
E19	NC					
E20	NC					
F1	V_{DDM}					
F2	D15					
F3	D29					
F4	V_{DDC}					
F5	V_{DDC}					
F6	V_{DDC}					
F7	GND					
F8	GND					
F9	GND					

Table 1. MSC7113 Signals by Ball Designator (continued)

Number	Signal Names					
	End of Reset	Software Controlled			Hardware Controlled	
		GPI Enabled (Default)	Interrupt Enabled	GPO Enabled	Primary	Alternate
K5	V_{DDM}					
K6	GND					
K7	GND					
K8	GND					
K9	GND					
K10	GND					
K11	GND					
K12	GND					
K13	GND					
K14	GND					
K15	V_{DDIO}					
K16	V_{DDIO}					
K17	V_{DDC}					
K18	reserved				HA0	
K19	reserved				HDDS	
K20	reserved				$\overline{\text{HDS}}$/HDS or $\overline{\text{HWR}}$/HWR	
L1	D1					
L2	GND					
L3	D3					
L4	V_{DDC}					
L5	V_{DDM}					
L6	GND					
L7	GND					
L8	GND					
L9	GND					
L10	GND					
L11	GND					
L12	GND					
L13	GND					
L14	V_{DDIO}					
L15	V_{DDIO}					
L16	V_{DDIO}					
L17	V_{DDC}					
L18 (1L44X)	reserved				$\overline{\text{HCS2}}$/HCS2	
L18 (1M88B)	GPIB11			GPOB11	$\overline{\text{HCS2}}$/HCS2	
L19	reserved				$\overline{\text{HCS1}}$/HCS1	
L20	reserved				HRW or $\overline{\text{HRD}}$/HRD	
M1	D2					

Table 1. MSC7113 Signals by Ball Designator (continued)

Number	Signal Names					
	End of Reset	Software Controlled			Hardware Controlled	
		GPI Enabled (Default)	Interrupt Enabled	GPO Enabled	Primary	Alternate
N20	V_{SSPLL}					
P1	D7					
P2	D17					
P3	D16					
P4	V_{DDM}					
P5	V_{DDM}					
P6	V_{DDM}					
P7	GND					
P8	GND					
P9	GND					
P10	GND					
P11	GND					
P12	GND					
P13	GND					
P14	GND					
P15	V_{DDIO}					
P16	V_{DDIO}					
P17	V_{DDC}					
P18	$\overline{\text{PORESET}}$					
P19	TPSEL					
P20	V_{DDPLL}					
R1	GND					
R2	D19					
R3	D18					
R4	V_{DDM}					
R5	V_{DDM}					
R6	V_{DDM}					
R7	GND					
R8	V_{DDM}					
R9	GND					
R10	V_{DDM}					
R11	GND					
R12	GND					
R13	V_{DDIO}					
R14	GND					
R15	V_{DDIO}					
R16	V_{DDIO}					
R17	V_{DDC}					

Table 1. MSC7113 Signals by Ball Designator (continued)

Number	Signal Names					
	End of Reset	Software Controlled			Hardware Controlled	
		GPI Enabled (Default)	Interrupt Enabled	GPO Enabled	Primary	Alternate
U16	V_{DDC}					
U17	V_{DDC}					
U18	reserved				COL	
U19	TCK					
U20	$\overline{\text{TRST}}$					
V1	V_{DDM}					
V2	NC					
V3	A13					
V4	A11					
V5	A10					
V6	A5					
V7	A2					
V8	BA0					
V9	NC					
V10	reserved				EVNT0	
V11	SWTE	GPIA16	$\overline{\text{IRQ12}}$	GPOA16	EVNT4	
V12	GPIA8		$\overline{\text{IRQ6}}$	GPOA8	T0TCK	
V13	GPIA4		$\overline{\text{IRQ1}}$	GPOA4	T1RFS	
V14	GPIA0		$\overline{\text{IRQ11}}$	GPOA0	T1TD	
V15	GPIA28		$\overline{\text{IRQ17}}$	GPOA28	TX_ER	reserved
V16	GPID6			GPOD6	RXD2	reserved
V17	GPIA22		$\overline{\text{IRQ22}}$	GPOA22	RXD0	
V18	GPIA24		$\overline{\text{IRQ24}}$	GPOA24	TX_EN	
V19	reserved				CRS	
V20	TDI					
W1	GND					
W2	V_{DDM}					
W3	A12					
W4	A8					
W5	A7					
W6	A6					
W7	A3					
W8	NC					
W9	GPIA17		$\overline{\text{IRQ13}}$	GPOA17	EVNT1	CLKO
W10	BM0	GPIC14		GPOC14	EVNT2	
W11	GPIA10		$\overline{\text{IRQ5}}$	GPOA10	T0RFS	
W12	GPIA7		$\overline{\text{IRQ7}}$	GPOA7	T0TFS	
W13	GPIA3		$\overline{\text{IRQ8}}$	GPOA3	T1RD	

2.5 AC Timings

This section presents timing diagrams and specifications for individual signals and parallel I/O outputs and inputs. All AC timings are based on a 30 pF load, except where noted otherwise, and a 50 Ω transmission line. For any additional pF, use the following equations to compute the delay:

- Standard interface: $2.45 + (0.054 \times C_{load})$ ns
- DDR interface: $1.6 + (0.002 \times C_{load})$ ns

2.5.1 Clock and Timing Signals

The following tables describe clock signal characteristics. **Table 6** shows the maximum frequency values for internal (core, reference, and peripherals) and external (CLKO) clocks. You must ensure that maximum frequency values are not exceeded (see for the allowable ranges when using the PLL).

Table 6. Maximum Frequencies

Characteristic	Maximum in MHz	
	Mask Set 1L44X	Mask Set 1M88B
Core clock frequency (CLOCK)	200	266
External output clock frequency (CLKO)	50	67
Memory clock frequency (CK, $\overline{CK}$)	100	133
TDM clock frequency (TxRCK, TxTCK)	50	67

Table 7. Clock Frequencies in MHz

Characteristic	Symbol	Min	Max	
			Mask Set 1L44X	Mask Set 1M88B
CLKIN frequency	F_{CLKIN}	10	100	100
CLOCK frequency	F_{CORE}	—	200	266
CK, $\overline{CK}$ frequency	F_{CK}	—	100	133
TDMxRCK, TDMxTCK frequency	F_{TDMCK}	—	50	50
CLKO frequency	F_{CKO}	—	50	67
AHB/IPBus/APB clock frequency	F_{BCK}	—	100	133
Note: The rise and fall time of external clocks should be 5 ns maximum				

Table 8. System Clock Parameters

Characteristic	Min	Max	Unit
CLKIN frequency	10	100	MHz
CLKIN slope	—	5	ns
CLKIN frequency jitter (peak-to-peak)	—	1000	ps
CLKO frequency jitter (peak-to-peak)	—	150	ps

2.5.2 Configuring Clock Frequencies

This section describes important requirements for configuring clock frequencies in the MSC7113 device when using the PLL block. To configure the device clocking, you must program four fields in the Clock Control Register (CLKCTL):

- PLLDVF field. Specifies the PLL division factor. The output of the divider block is the input to the multiplier block.
- PLLMLTF field. Specifies the PLL multiplication factor. The output from the multiplier block is the VCO.
- RNG field. Selects the available PLL frequency range.
- CKSEL field. Selects the source for the core clock.

There are restrictions on the frequency range permitted at the beginning of the multiplication portion of the PLL that affect the allowable values for the PLLDVF and PLLMLTF fields. The following sections define these restrictions and provide guidelines to configure the device clocking when using the PLL. Refer to the Clock and Power Management chapter in the *MSC711x Reference Manual* for details on the clock programming model.

2.5.2.1 PLL Multiplier Restrictions

There are two restrictions for correct usage of the PLL block:

- The input frequency to the PLL multiplier block (that is, the output of the divider) must be in the range 10.5–19.5 MHz.
- The output frequency of the PLL multiplier must be in the range 300-600 MHz.

When programming the PLL for a desired output frequency using the PLLDVF, PLLMLTF, and RNG fields, you must meet these constraints.

2.5.2.2 Division Factors and Corresponding CLKIN Frequency Range

The value of the PLLDVF field determines the allowable CLKIN frequency range, as shown in **Table 9**.

Table 9. CLKIN Frequency Ranges by Divide Factor Value

PLLDVF Field Value	Divide Factor	CLKIN Frequency Range	Comments
0x00	1	10.5 to 19.5 MHz	Pre-Division by 1
0x01	2	21 to 39 MHz	Pre-Division by 2
0x02	3	31.5 to 58.5 MHz	Pre-Division by 3
0x03	4	42 to 78 MHz	Pre-Division by 4
0x04	5	52.5 to 97.5 MHz	Pre-Division by 5
0x05	6	63 to 100 MHz	Pre-Division by 6
0x06	7	73.5 to 100 MHz	Pre-Division by 7
0x07	8	84 to 100 MHz	Pre-Division by 8
0x08	9	94.5 to 100 MHz	Pre-Division by 9
Note: The maximum CLKIN frequency is 100 MHz. Therefore, the PLLDVF value must be in the range from 1–9.			

2.5.2.3 Multiplication Factor Range

The multiplier block output frequency ranges depend on the divided input clock frequency as shown in **Table 10**.

Table 10. PLLMLTF Ranges

Multiplier Block (Loop) Output Range	Minimum PLLMLTF Value	Maximum PLLMLTF Value
266 ≤ [Divided Input Clock × (PLLMLTF + 1)] ≤ 532 MHz	266/Divided Input Clock	532/Divided Input Clock
Note: This table results from the allowed range for F_{Loop}. The minimum and maximum multiplication factors are dependent on the frequency of the Divided Input Clock.		

2.5.2.4 Allowed Core Clock Frequency Range

The frequency delivered to the core, extended core, and peripherals depends on the value of the CLKCTRL[RNG] bit as shown in **Table 11**.

Table 11. F_{vco} Frequency Ranges

CLKCTRL[RNG] Value	Allowed Range of F_{vco}
1	$266 \le F_{vco} \le 532$ MHz
0	$133 \le F_{vco} \le 266$ MHz
Note: This table results from the allowed range for F_{vco}, which is F_{Loop} modified by CLKCTRL[RNG].	

This bit along with the CKSEL determines the frequency range of the core clock.

Table 12. Resulting Ranges Permitted for the Core Clock

CLKCTRL[CKSEL]	CLKCTRL[RNG]	Resulting Division Factor	Allowed Range of Core Clock	Comments
11	1	1	Reserved	Reserved
11	0	2	133 ≤ core clock ≤ 266 MHz	Limited by range of PLL
01	1	2	133 ≤ core clock ≤ 266 MHz	Limited by range of PLL
01	0	4	66.5 ≤ core clock ≤ 133 MHz	Limited by range of PLL
Note: This table results from the allowed range for F_{OUT}, which depends on clock selected via CLKCTRL[CKSEL].				

2.5.2.5 Core Clock Frequency Range When Using DDR Memory

The core clock can also be limited by the frequency range of the DDR devices in the system. **Table 13** summarizes this restriction.

Table 13. Core Clock Ranges When Using DDR

DDR Type	Allowed Frequency Range for DDR CK	Corresponding Range for the Core Clock	Comments
DDR 200 (PC-1600)	83–100 MHz	166 ≤ core clock ≤ 200 MHz	Core limited to 2 × maximum DDR frequency
DDR 266 (PC-2100)	83–133 MHz	166 ≤ core clock ≤ 266 MHz	Core limited to 2 × maximum DDR frequency
DDR 333 (PC-2600)	83–150 MHz	166 ≤ core clock ≤ 300 MHz	Core limited to 2 × maximum DDR frequency

2.5.3 Reset Timing

The MSC7113 device has several inputs to the reset logic. All MSC7113 reset sources are fed into the reset controller, which takes different actions depending on the source of the reset. The reset status register indicates the most recent sources to cause a reset. **Table 14** describes the reset sources.

Table 14. Reset Sources

Name	Direction	Description
Power-on reset (PORESET)	Input	Initiates the power-on reset flow that resets the MSC7113 and configures various attributes of the MSC7113. On PORESET, the entire MSC7113 device is reset. SPLL and DLL states are reset, HRESET is driven, the SC1400 extended core is reset, and system configuration is sampled. The system is configured only when PORESET is asserted.
External Hard reset (HRESET)	Input/ Output	Initiates the hard reset flow that configures various attributes of the MSC7113. While HRESET is asserted, HRESET is an open-drain output. Upon hard reset, HRESET is driven and the SC1400 extended core is reset.
Software watchdog reset	Internal	When the MSC7113 watchdog count reaches zero, a software watchdog reset is signalled. The enabled software watchdog event then generates an internal hard reset sequence.
Bus monitor reset	Internal	When the MSC7113 bus monitor count reaches zero, a bus monitor hard reset is asserted. The enabled bus monitor event then generates an internal hard reset sequence.
JTAG EXTEST, CLAMP, or HIGHZ command	Internal	When a Test Access Port (TAP) executes an EXTEST, CLAMP, or HIGHZ command, the TAP logic asserts an internal reset signal that generates an internal soft reset sequence.

Table 15 summarizes the reset actions that occur as a result of the different reset sources.

Table 20. TDM Timing

No.	Characteristic	Expression	Min	Max	Units
307	TDMxTCK High to TDMxTD output valid		—	14.0	ns
308	TDMxTD hold time		2.0	—	ns
309	TDMxTCK High to TDMxTD output high impedance		—	10.0	ns
310	TDMXTFS/TDMxRFS output valid		—	13.5	ns
311	TDMxTFS/TDMxRFS output hold time		2.5	—	ns

Notes:
1. Output values are based on 30 pF capacitive load.
2. Inputs are referenced to the sampling that the TDM is programmed to use. Outputs are referenced to the programming edge they are programmed to use. Use of the rising edge or falling edge as a reference is programmable. Refer to the *MSC711x Reference Manual* for details. TDMxTCK and TDMxRCK are shown using the rising edge.

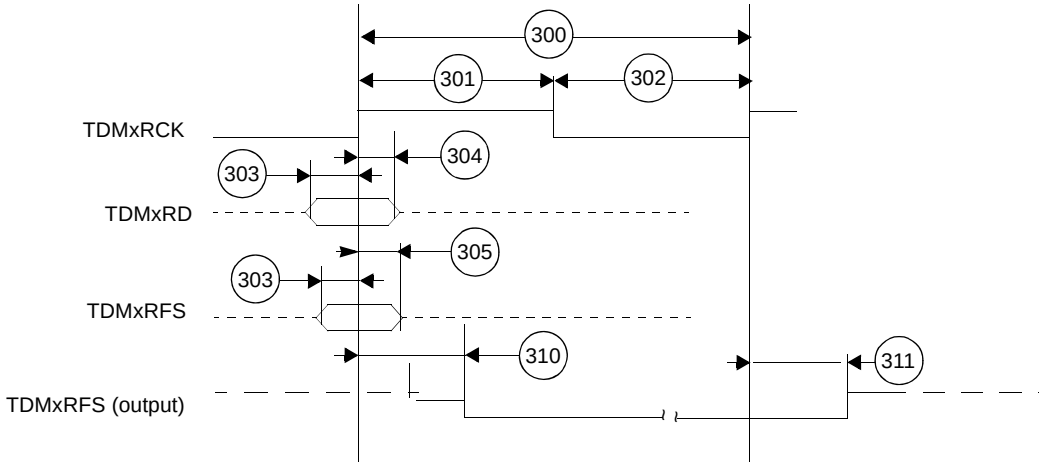

Figure 8. TDM Receive Signals

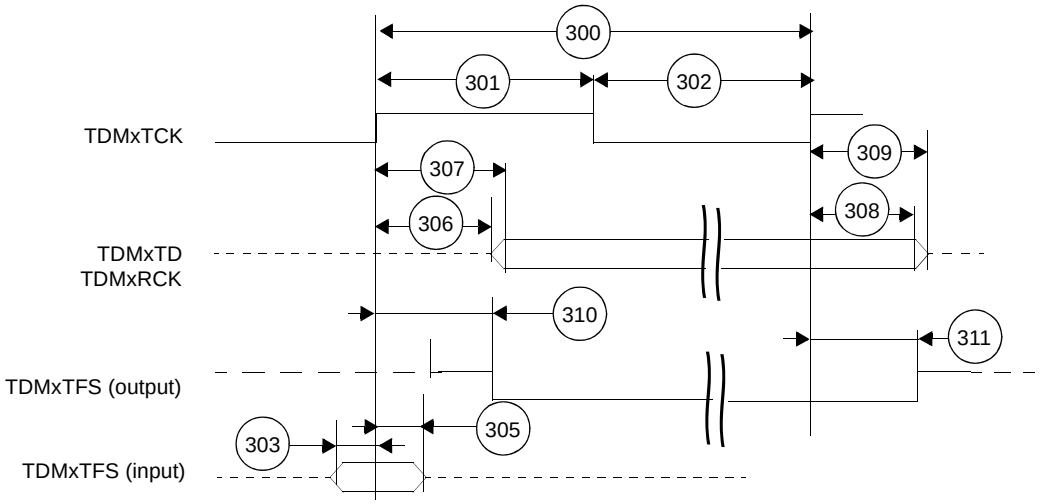

Figure 9. TDM Transmit Signals

2.5.7 HDI16 Signals

Table 25. Host Interface (HDI16) Timing[1, 2]

No.	Characteristics[3]	Mask Set 1L44X		Mask Set 1M88B		Unit
		Expression	Value	Expression	Value	
40	Host Interface Clock period	T_{HCLK}	Note 1	T_{CORE}	Note 1	ns
44a	Read data strobe minimum assertion width[4] HACK read minimum assertion width	$3.0 \times T_{HCLK}$	Note 11	$2.0 \times T_{CORE} + 9.0$	Note 11	ns
44b	Read data strobe minimum deassertion width[4] HACK read minimum deassertion width	$1.5 \times T_{HCLK}$	Note 11	$1.5 \times T_{CORE}$	Note 11	ns
44c	Read data strobe minimum deassertion width[4] after "Last Data Register" reads[5,6], or between two consecutive CVR, ICR, or ISR reads[7] HACK minimum deassertion width after "Last Data Register" reads[5,6]	$2.5 \times T_{HCLK}$	Note 11	$2.5 \times T_{CORE}$	Note 11	ns
45	Write data strobe minimum assertion width[8] HACK write minimum assertion width	$1.5 \times T_{HCLK}$	Note 11	$1.5 \times T_{CORE}$	Note 11	ns
46	Write data strobe minimum deassertion width[8] HACK write minimum deassertion width after ICR, CVR and Data Register writes[5]	$2.5 \times T_{HCLK}$	Note 11	$2.5 \times T_{CORE}$	Note 11	ns
47	Host data input minimum setup time before write data strobe deassertion[8] Host data input minimum setup time before HACK write deassertion	—	3.0	—	2.5	ns
48	Host data input minimum hold time after write data strobe deassertion[8] Host data input minimum hold time after HACK write deassertion	—	4.0	—	2.5	ns
49	Read data strobe minimum assertion to output data active from high impedance[4] HACK read minimum assertion to output data active from high impedance	—	1.0	—	1.0	ns
50	Read data strobe maximum assertion to output data valid[4] HACK read maximum assertion to output data valid	$(2.0 \times T_{HCLK}) + 8.0$	Note 11	$(2.0 \times T_{CORE}) + 8.0$	Note 11	ns
51	Read data strobe maximum deassertion to output data high impedance[4] HACK read maximum deassertion to output data high impedance	—	8.0	—	9.0	ns
52	Output data minimum hold time after read data strobe deassertion[4] Output data minimum hold time after HACK read deassertion	—	1.0	—	1.0	ns
53	HCS[1–2] minimum assertion to read data strobe assertion[4]	—	0.0	—	0.5	ns
54	HCS[1–2] minimum assertion to write data strobe assertion[8]	—	0.0	—	0.0	ns
55	HCS[1–2] maximum assertion to output data valid	$(2.0 \times T_{HCLK}) + 8.0$	Note 11	$(2.0 \times T_{CORE}) + 6.0$	Note 11	ns
56	HCS[1–2] minimum hold time after data strobe deassertion[9]	—	0.0	—	0.5	ns
57	HA[0–3], HRW minimum setup time before data strobe assertion[9]	—	5.0	—	5.0	ns
58	HA[0–3], HRW minimum hold time after data strobe deassertion[9]	—	5.0	—	5.0	ns
61	Maximum delay from read data strobe deassertion to host request deassertion for "Last Data Register" read[4, 5, 10]	$(3.0 \times T_{HCLK}) + 8.0$	Note 11	$(3.0 \times T_{CORE}) + 6.0$	Note 11	ns
62	Maximum delay from write data strobe deassertion to host request deassertion for "Last Data Register" write[5,8,10]	$(3.0 \times T_{HCLK}) + 8.0$	Note 11	$(3.0 \times T_{CORE}) + 6.0$	Note 11	ns
63	Minimum delay from DMA HACK (OAD=0) or Read/Write data strobe(OAD=1) deassertion to HREQ assertion.	$(2.0 \times T_{HCLK}) + 1.0$	Note 11	$(2.0 \times T_{CORE}) + 1.0$	Note 11	ns
64	Maximum delay from DMA HACK (OAD=0) or Read/Write data strobe(OAD=1) assertion to HREQ deassertion	$(5.0 \times T_{HCLK}) + 8.0$	Note 11	$(5.0 \times T_{CORE}) + 6.0$	Note 11	ns

Table 25. Host Interface (HDI16) Timing[1, 2] (continued)

No.	Characteristics[3]	Mask Set 1L44X		Mask Set 1M88B		Unit
		Expression	Value	Expression	Value	

Notes:
1. T_{HCLK} = 2/ (Core Clock). At 200 MHz, T_{HCLK} = 10 ns. T_{CORE} = core clock period. At 266 MHz, T_{CORE} = 3.75 ns.
2. In the timing diagrams below, the controls pins are drawn as active low. The pin polarity is programmable.
3. V_{DD} = 3.3 V ± 0.15 V; T_J = –40°C to +105 °C, C_L = 30 pF for maximum delay timings and C_L = 0 pF for minimum delay timings.
4. The read data strobe is $\overline{\text{HRD}}$/HRD in the dual data strobe mode and $\overline{\text{HDS}}$/HDS in the single data strobe mode.
5. For 64-bit transfers, The “last data register” is the register at address 0x7, which is the last location to be read or written in data transfers. This is RX0/TX0 in the little endian mode (HBE = 0), or RX3/TX3 in the big endian mode (HBE = 1).
6. This timing is applicable only if a read from the “last data register” is followed by a read from the RXL, RXM, or RXH registers without first polling RXDF or HREQ bits, or waiting for the assertion of the $\overline{\text{HREQ}}$/HREQ signal.
7. This timing is applicable only if two consecutive reads from one of these registers are executed.
8. The write data strobe is HWR in the dual data strobe mode and HDS in the single data strobe mode.
9. The data strobe is host read ($\overline{\text{HRD}}$/HRD) or host write ($\overline{\text{HWR}}$/HWR) in the dual data strobe mode and host data strobe ($\overline{\text{HDS}}$/HDS) in the single data strobe mode.
10. The host request is $\overline{\text{HREQ}}$/HREQ in the single host request mode and $\overline{\text{HRRQ}}$/HRRQ and $\overline{\text{HTRQ}}$/HTRQ in the double host request mode. $\overline{\text{HRRQ}}$/HRRQ is deasserted only when HOTX fifo is empty, $\overline{\text{HTRQ}}$/HTRQ is deasserted only if HORX fifo is full (treat as level Host Request).
11. Compute the value using the expression.
12. For mask set 1M88B, the read and write data strobe minimum deassertion width for non-”last data register” accesses in single and dual data strobe modes is based on timings 57 and 58.

Figure 14 and **Figure 15** show HDI16 read signal timing. **Figure 16** and **Figure 17** show HDI16 write signal timing.

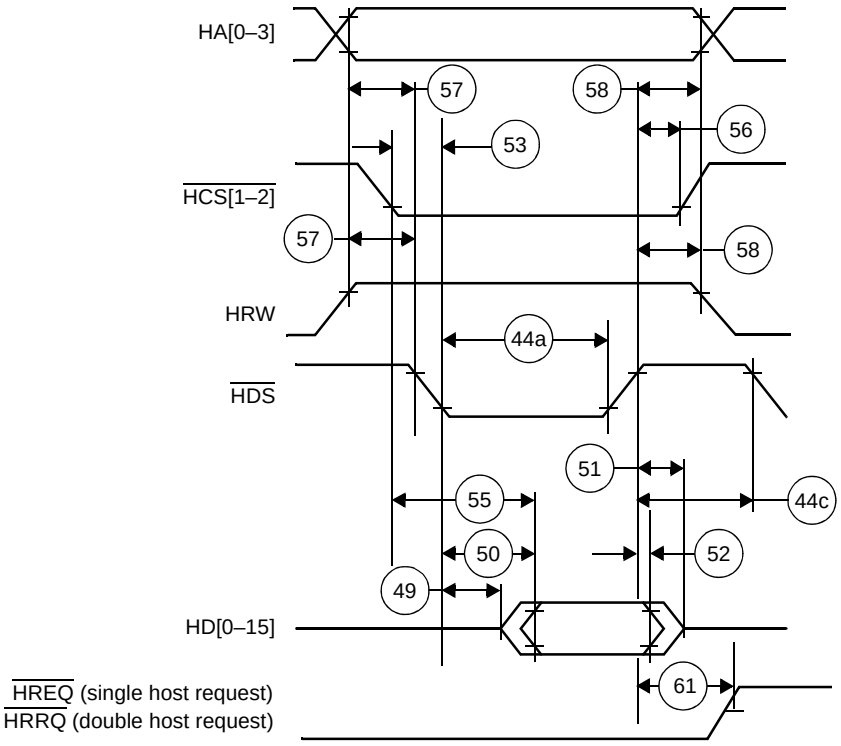

Figure 14. Read Timing Diagram, Single Data Strobe

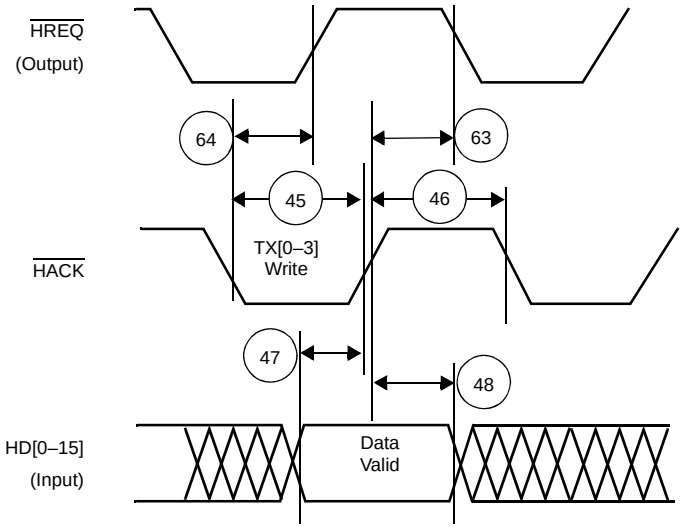

Figure 19. Host DMA Write Timing Diagram, HPCR[OAD] = 0

3 Hardware Design Considerations

This section described various areas to consider when incorporating the MSC7113 device into a system design.

3.1 Thermal Design Considerations

An estimation of the chip-junction temperature, T_J, in °C can be obtained from the following:

$$T_J = T_A + (R_{\theta JA} \times P_D) \quad \textit{Eqn. 1}$$

where

T_A = ambient temperature near the package (°C)

$R_{\theta JA}$ = junction-to-ambient thermal resistance (°C/W)

$P_D = P_{INT} + P_{I/O}$ = power dissipation in the package (W)

$P_{INT} = I_{DD} \times V_{DD}$ = internal power dissipation (W)

$P_{I/O}$ = power dissipated from device on output pins (W)

The power dissipation values for the MSC7113 are listed in **Table 4**. The ambient temperature for the device is the air temperature in the immediate vicinity that would cool the device. The junction-to-ambient thermal resistances are JEDEC standard values that provide a quick and easy estimation of thermal performance. There are two values in common usage: the value determined on a single layer board and the value obtained on a board with two planes. The value that more closely approximates a specific application depends on the power dissipated by other components on the printed circuit board (PCB). The value obtained using a single layer board is appropriate for tightly packed PCB configurations. The value obtained using a board with internal planes is more appropriate for boards with low power dissipation (less than 0.02 W/cm^2 with natural convection) and well separated components. Based on an estimation of junction temperature using this technique, determine whether a more detailed thermal analysis is required. Standard thermal management techniques can be used to maintain the device thermal junction temperature below its maximum. If T_J appears to be too high, either lower the ambient temperature or the power dissipation of the chip.

You can verify the junction temperature by measuring the case temperature using a small diameter thermocouple (40 gauge is recommended) or an infrared temperature sensor on a spot on the device case. Use the following equation to determine T_J:

$$T_J = T_T + (\Psi_{JT} \times P_D) \quad \textit{Eqn. 2}$$

where

T_T = thermocouple (or infrared) temperature on top of the package (°C)

Ψ_{JT} = thermal characterization parameter (°C/W)

P_D = power dissipation in the package (W)

3.2 Power Supply Design Considerations

This section outlines the MSC7113 power considerations: power supply, power sequencing, power planes, decoupling, power supply filtering, and power consumption. It also presents a recommended power supply design and options for low-power consumption. For information on AC/DC electrical specifications and thermal characteristics, refer to **Section 2**.

3.2.1 Power Supply

The MSC7113 requires four input voltages, as shown in **Table 32**.

Table 32. MSC7113 Voltages

Voltage	Symbol	Value
Core	V_{DDC}	1.2 V
Memory	V_{DDM}	2.5 V
Reference	V_{REF}	1.25 V
I/O	V_{DDIO}	3.3 V

You should supply the MSC7113 core voltage via a variable switching supply or regulator to allow for compatibility with possible core voltage changes on future silicon revisions. The core voltage is supplied with 1.2 V (+5% and –10%) across V_{DDC} and GND and the I/O section is supplied with 3.3 V (± 10%) across V_{DDIO} and GND. The memory and reference voltages supply the DDR memory controller block. The memory voltage is supplied with 2.5 V across V_{DDM} and GND. The reference voltage is supplied across V_{REF} and GND and must be between $0.49 \times V_{DDM}$ and $0.51 \times V_{DDM}$. Refer to the JEDEC standard JESD8 (*Stub Series Terminated Logic for 2.5 Volts* (STTL_2)) for memory voltage supply requirements.

3.2.2 Power Sequencing

One consequence of multiple power supplies is that the voltage rails ramp up at different rates when power is initially applied. The rates depend on the power supply, the type of load on each power supply, and the way different voltages are derived. It is extremely important to observe the power up and power down sequences at the board level to avoid latch-up, forward biasing of ESD devices, and excessive currents, which all lead to severe device damage.

Note: There are five possible power-up/power-down sequence cases. The first four cases listed in the following sections are recommended for new designs. The fifth case is not recommended for new designs and must be carefully evaluated for current spike risks based on actual information for the specific application.

3.2.3 Power Planes

Each power supply pin (V_{DDC}, $V_{DDM,}$ and V_{DDIO}) should have a low-impedance path to the board power supply. Each GND pin should be provided with a low-impedance path to ground. The power supply pins drive distinct groups of logic on the device. The MSC7113 V_{DDC} power supply pins should be bypassed to ground using decoupling capacitors. The capacitor leads and associated printed circuit traces connecting to device power pins and GND should be kept to less than half an inch per capacitor lead. A minimum four-layer board that employs two inner layers as power and GND planes is recommended. See **Section 3.5** for DDR Controller power guidelines.

3.2.4 Decoupling

Both the I/O voltage and core voltage should be decoupled for switching noise. For I/O decoupling, use standard capacitor values of 0.01 µF for every two to three voltage pins. For core voltage decoupling, use two levels of decoupling. The first level should consist of a 0.01 µF high frequency capacitor with low effective series resistance (ESR) and effective series inductance (ESL) for every two to three voltage pins. The second decoupling level should consist of two bulk/tantalum decoupling capacitors, one 10 µF and one 47 µF, (with low ESR and ESL) mounted as closely as possible to the MSC7113 voltage pins. Additionally, the maximum drop between the power supply and the DSP device should be 15 mV at 1 A.

3.2.5 PLL Power Supply Filtering

The MSC7113 V_{DDPLL} power signal provides power to the clock generation PLL. To ensure stability of the internal clock, the power supplied to this pin should be filtered with capacitors that have low and high frequency filtering characteristics. V_{DDPLL} can be connected to V_{DDC} through a 2 Ω resistor. V_{SSPLL} can be tied directly to the GND plane. A circuit similar to the one shown in **Figure 35** is recommended. The PLL loop filter should be placed as closely as possible to the V_{DDPLL} pin (which are located on the outside edge of the silicon package) to minimize noise coupled from nearby circuits.The 0.01 µF capacitor should be closest to V_{DDPLL}, followed by the 0.1 µF capacitor, the 10 µF capacitor, and finally the 2-Ω resistor to V_{DDC}. These traces should be kept short.

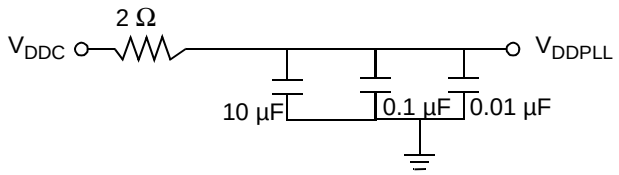

Figure 35. PLL Power Supply Filter Circuits

3.2.6 Power Consumption

You can reduce power consumption in your design by controlling the power consumption of the following regions of the device:

- *Extended core.* Use the SC1400 Stop and Wait modes by issuing a **stop** or **wait** instruction.
- *Clock synthesis module.* Disable the PLL, timer, watchdog, or DDR clocks or disable the CLKO pin.
- *AHB subsystem.* Freeze or shut down the AHB subsystem using the GPSCTL[XBR_HRQ] bit.
- *Peripheral subsystem.* Halt the individual on-device peripherals such as the DDR memory controller, Ethernet MAC, HDI16, TDM, UART, I^2C, and timer modules.

For details, see the “Clocks and Power Management” chapter of the *MSC711x Reference Manual*.

3.2.7 Power Supply Design

One of the most common ways to derive power is to use either a simple fixed or adjustable linear regulator. For the system I/O voltage supply, a simple fixed 3.3 V supply can be used. However, a separate adjustable linear regulator supply for the core voltage V_{DDC} should be implemented. For the memory power supply, regulators are available that take care of all DDR power requirements.

Table 33. Recommended Power Supply Ratings

Supply	Symbol	Nominal Voltage	Current Rating
Core	V_{DDC}	1.2 V	1.5 A per device
Memory	V_{DDM}	2.5 V	0.5 A per device
Reference	V_{REF}	1.25 V	10 µA per device
I/O	V_{DDIO}	3.3 V	1.0 A per device

3.3 Estimated Power Usage Calculations

The following equations permit estimated power usage to be calculated for individual design conditions. Overall power is derived by totaling the power used by each of the major subsystems:

$$P_{TOTAL} = P_{CORE} + P_{PERIPHERALS} + P_{DDRIO} + P_{IO} + P_{LEAKAGE} \quad \textit{Eqn. 3}$$

This equation combines dynamic and static power. Dynamic power is determined using the generic equation:

$$C \times V^2 \times F \times 10^{-3}\ mW \quad \textit{Eqn. 4}$$

where,

C = load capacitance in pF

V = peak-to-peak voltage swing in V

F = frequency in MHz

3.3.1 Core Power

Estimation of core power is straightforward. It uses the generic dynamic power equation and assumes that the core load capacitance is 750 pF, core voltage swing is 1.2 V, and the core frequency is 200 MHz or 266 MHz. This yields:

$$P_{CORE} = 750\ pF \times (1.2\ V)^2 \times 200\ MHz \times 10^{-3} = 216\ mW \quad \textit{Eqn. 5}$$

$$P_{CORE} = 750\ pF \times (1.2\ V)^2 \times 266\ MHz \times 10^{-3} = 287\ mW \quad \textit{Eqn. 6}$$

This equation allows for adjustments to voltage and frequency if necessary.

3.3.4 External I/O Power

The estimation of the I/O power is similar to the computation of the peripheral power estimates. The power consumption per signal line is computed assuming a maximum load of 20 pF, a voltage swing of 3.3 V, and a switching frequency of 25 MHz or 33 MHz, which yields:

$$P_{IO} = 20\ pF \times (3.3\ V)^2 \times 25\ MHz \times 10^{-3} = 5.44\ mW\ per\ I/O\ line \quad \text{Eqn. 16}$$

$$P_{IO} = 20\ pF \times (3.3\ V)^2 \times 33\ MHz \times 10^{-3} = 7.19\ mW\ per\ I/O\ line \quad \text{Eqn. 17}$$

Multiply this number by the number of I/O signal lines used in the application design to compute the total I/O power.

Note: The signal loading depends on the board routing. For systems using a single DDR device, the load could be as low as 7 pF.

3.3.5 Leakage Power

The leakage power is for all power supplies combined at a specific temperature. The value is temperature dependent. The observed leakage value at room temperature is 64 mW.

3.3.6 Example Total Power Consumption

Using the examples in this section and assuming four peripherals and 10 I/O lines active, a total power consumption value is estimated as the following:

$$P_{TOTAL}\ (200\ MHz\ core) = 216 + (4 \times 2.88) + 324{,}2 + (10 \times 5.44) + 64 = 670.12\ mW \quad \text{Eqn. 18}$$

$$P_{TOTAL}\ (266\ MHz\ core) = 287 + (4 \times 3.83) + 326.3 + (10 \times 7.19) + 64 = 764.52\ mW \quad \text{Eqn. 19}$$

3.4 Reset and Boot

This section describes the recommendations for configuring the MSC7113 at reset and boot.

3.4.1 Reset Circuit

$\overline{\text{HRESET}}$ is a bidirectional signal and, if driven as an input, should be driven with an open collector or open-drain device. For an open-drain output such as $\overline{\text{HRESET}}$, take care when driving many buffers that implement input bus-hold circuitry. The bus-hold currents can cause enough voltage drop across the pull-up resistor to change the logic level to low. Either a smaller value of pull-up or less current loading from the bus-hold drivers overcomes this issue. To avoid exceeding the MSC7113 output current, the pull-up value should not be too small (a 1 KΩ pull-up resistor is used in the MSC711xADS reference design).

3.4.2 Reset Configuration Pins

Table 34 shows the MSC7113 reset configuration signals. These signals are sampled at the deassertion (rising edge) of PORESET. For details, refer to the Reset chapter of the *MSC711x Reference Manual*.

Table 34. Reset Configuration Signals

Signal	Description	Settings	
BM[1–0]	Determines boot mode.	0	Boot from HDI16 port.
		01	Boot from I2C.
		1x	Reserved.
SWTE	Determines watchdog functionality.	0	Watchdog timer disabled.
		1	Watchdog timer enabled.
HDSP	Configures HDI16 strobe polarity.	0	Host Data strobes active low.
		1	Host Data strobes active high.
H8BIT	Configures HDI16 operation mode.	0	HDI16 port configured for 16-bit operation.
		1	HDI16 port configured for 8-bit operation.

3.4.3 Boot

After a power-on reset, the PLL is bypassed and the device is directly clocked from the CLKIN pin. Using this input clock, the system initializes using the boot loader program that resides in the internal ROM. After initialization, the DSP core can enable the PLL and start the device operating at a higher speed. The MSC7113 can boot from an external host through the HDI16 or download a user program through the I^2C port. The boot operating mode is set by configuring the BM[1–0] signals sampled at the rising edge of PORESET, as shown in **Table 35**.

Table 35. Boot Mode Settings

BM1	BM0	Boot Source
0	0	External host via HDI16 with the PLL disabled.
0	1	I^2C.
1	0	External host via the HDI16 with the PLL enabled.
1	1	Reserved.

3.4.3.1 HDI16 Boot

If the MSC7113 device boots from an external host through the HDI16, the port is configured as follows:

- Operate in Non-DMA mode.
- Operate in polled mode on the device side.
- Operate in polled mode on the external host side.
- External host must write four 16-bit values at a time with the first word as the most significant and the fourth word as the least significant.

When booting from a power-on reset, the HDI16 is additionally configurable as follows:

- 8- or 16-bit mode as specified by the H8BIT pin.
- Data strobe as specified by the HDSP and HDDS pins.

These pins are sampled only on the deassertion of power-on reset. During a boot from a hard reset, the configuration of these pins is unaffected.

Note: When the HDI16 is used for booting or other purposes, bit 0 is the least significant bit and not the most significant bit as for other DSP products.

3.4.3.2 I²C Boot

When the MSC7113 device is configured to boot from the I²C port, the boot program configures the GPIO pins shared with the I²C pins as I²C pins. The I²C interface is configured as follows:

- I²C in master mode.
- EPROM in slave mode.

For details on the boot procedure, see the “Boot Program” chapter of the *MSC711x Reference Manual*.

3.5 DDR Memory System Guidelines

MSC7113 devices contain a memory controller that provides a glueless interface to external double data rate (DDR) SDRAM memory modules with Class 2 Series Stub Termination Logic 2.5 V (SSTL_2). There are two termination techniques, as shown in Figure 36. Technique B is the most popular termination technique.

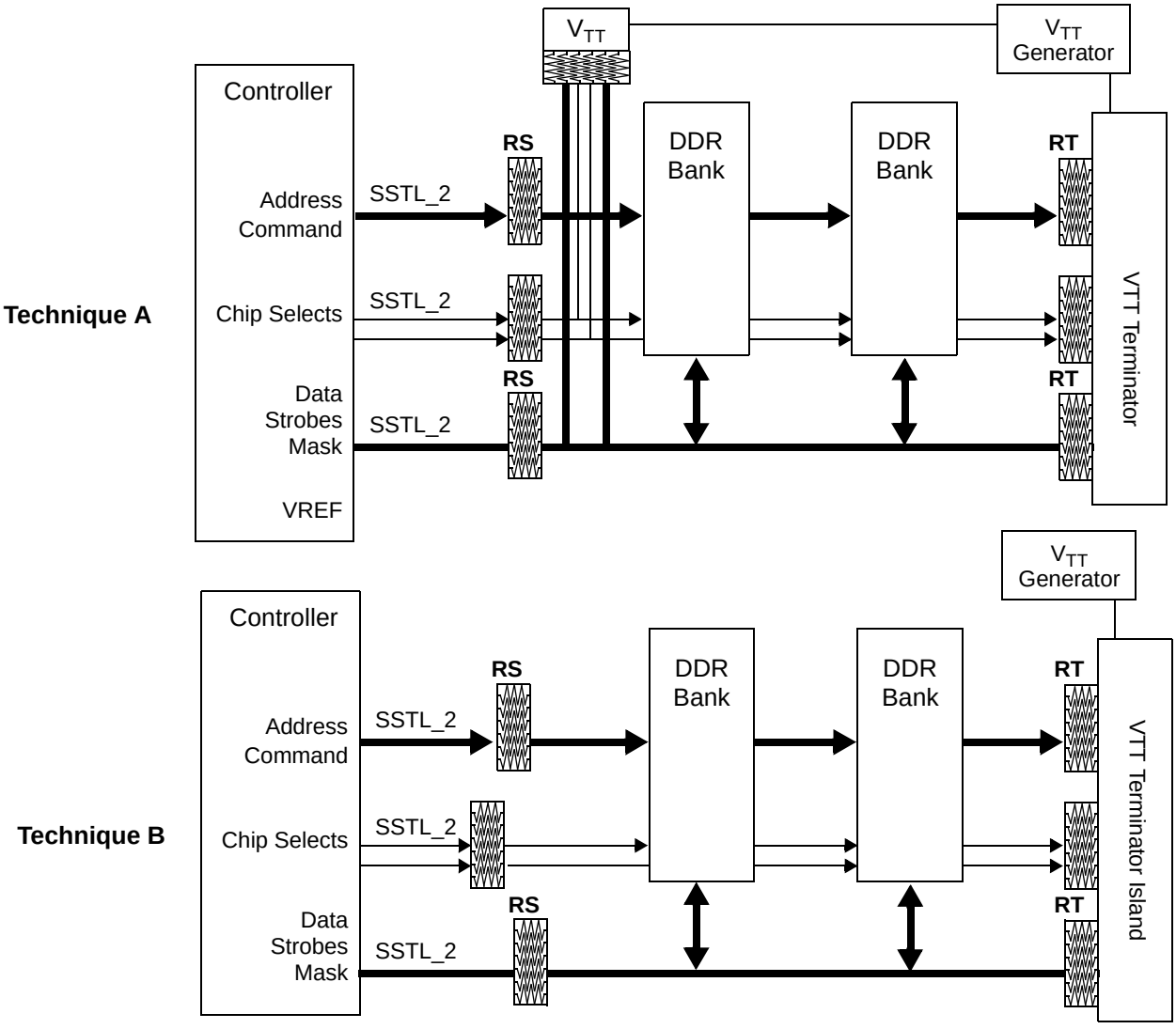

Figure 36. SSTL Termination Techniques

Figure 37 illustrates the power wattage for the resistors. Typical values for the resistors are as follows:

- RS = 22 Ω
- RT = 24 Ω